

The documentation and process conversion measures necessary to comply with this revision shall be completed by 8 July 2015.

INCH-POUND

MIL-PRF-19500/336M
8 April 2015
SUPERSEDING
MIL-PRF-19500/336L
30 January 2012

PERFORMANCE SPECIFICATION SHEET
TRANSISTOR, DUAL, UNITIZED, PNP, RADIATION HARDENED, SILICON, TYPES
2N3810, AND 2N3811, JAN, JANTX, JANTXV, JANS, JANHC, AND JANKC

This specification is approved for use by all Departments
and Agencies of the Department of Defense.

The requirements for acquiring the product described herein shall consist of
this specification sheet and [MIL-PRF-19500](#).

1. SCOPE

- * 1.1 Scope. This specification covers the performance requirements for two electrically isolated, matched PNP, radiation hardened, silicon transistors as one dual unit for use in particular switching applications. Four levels of product assurance are provided for each encapsulated device (JAN, JANTX, JANTXV, and JANS), and two levels of product assurance are provided for each unencapsulated device (JANHC and JANKC).
- * 1.2 Package outlines. The device package outlines are as follows: TO-78 in accordance with [figure 1](#) and U suffix in accordance with [figure 2](#) for all encapsulated device types. The dimensions and topography for JANHC and JANKC unencapsulated die are in accordance with figures [3](#) and [4](#).

1.3 Maximum ratings, unless otherwise specified, $T_C = +25^\circ\text{C}$.

Type	I_C	V_{CBO}	V_{CEO}	V_{EBO}
	<u>mA dc</u>	<u>V dc</u>	<u>V dc</u>	<u>V dc</u>
All types	50	60	60	5

P_T (1) $T_A = +25^\circ\text{C}$		P_T (2) $T_C = +25^\circ\text{C}$		$R_{\theta JA}$		$R_{\theta JC}$ (3)		T_J and T_{STG}
One section	Both sections	One section	Both sections	One section	Both sections	One section	Both sections	
<u>mW</u>	<u>mW</u>	<u>mW</u>	<u>mW</u>	$^\circ\text{C/W}$	$^\circ\text{C/W}$	$^\circ\text{C/W}$	$^\circ\text{C/W}$	<u>$^\circ\text{C}$</u>
(4) 200	(4) 350	300	450	875	500	583	350	-65 to +200

- (1) For $T_A > +25^\circ\text{C}$, derate linearly 1.143 mW/ $^\circ\text{C}$, one section; 2.000 mW/ $^\circ\text{C}$, both sections. See [figure 5](#) and [6](#).
- (2) For $T_C > +25^\circ\text{C}$, derate linearly 1.714 mW/ $^\circ\text{C}$, one section; 2.571 mW/ $^\circ\text{C}$, both sections.
- (3) For TO-78 devices only.
- (4) For non-thermal conductive PCB or unknown PCB surface mount conditions in free air, substitute figures 5 and 6 for the U package and use $R_{\theta JA}$.

Comments, suggestions, or questions on this document should be addressed to DLA Land and Maritime, ATTN: VAC, P.O. Box 3990, Columbus, OH 43218-3990, or emailed to Semiconductor@dla.mil. Since contact information can change, you may want to verify the currency of this address information using the ASSIST Online database at <https://assist.dla.mil>.



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1.4 Primary electrical characteristics at $T_A = +25^\circ$, pulsed (see 4.5.2).

Limit	h_{FE3} through h_{FE4} $V_{CE} = 5 \text{ V dc};$ $I_C = 100 \mu\text{A dc}$ Through $I_C = 1 \text{ mA dc}$	$ h_{fe} _2$ $V_{CE} = 5 \text{ V dc};$ $I_C = 1 \text{ mA dc};$ $f = 100 \text{ MHz}$	$V_{BE(sat) 2}$ $I_C = 1 \text{ mA dc};$ $I_B = 100 \mu\text{A dc}$	$V_{CE(sat) 2}$ $I_C = 1 \text{ mA dc};$ $I_B = 100 \mu\text{A dc}$
Minimum	2N3810 150	2N3811 300	1	V_{dc} 0.8
Maximum	450	900	5	0.25

1.5 Primary electrical matching characteristics of each individual section.

Limit	$\frac{h_{FE3-1}}{h_{FE3-2}}$ $V_{CE} = 5 \text{ V dc};$ $I_C = 100 \mu\text{A dc}$ (1)	$ V_{BE1} - V_{BE2} _2$ $V_{CE} = 5 \text{ V dc};$ $I_C = 100 \mu\text{A dc}$	$ \Delta(V_{BE1} - V_{BE2}) \Delta T_A _1$ $V_{CE} = 5 \text{ V dc}$ $I_C = 100 \mu\text{A dc}$ $T_A = +25^\circ\text{C and } -55^\circ\text{C}$	$ \Delta(V_{BE1} - V_{BE2}) \Delta T_A _2$ $V_{CE} = 5 \text{ V dc};$ $I_C = 100 \mu\text{A dc}$ $T_A = +125^\circ\text{C and } +25^\circ\text{C}$
		mV dc	mV dc	mV dc
Minimum	0.9			
Maximum	1.0	3	0.8	1.0

(1) The larger number will be placed in the denominator.

- * 1.5 Part or Identifying Number (PIN). The PIN is in accordance with MIL-PRF-19500, and as specified herein. See 6.4 for PIN construction example and 6.5 for a list of available PINs.
- * 1.5.1 JAN certification mark and quality level for encapsulated devices. The quality level designators for encapsulated devices that are applicable for this specification sheet from the lowest to the highest level are as follows: "JAN", "JANTX", "JANTXV" and "JANS".
- * 1.5.2 JAN certification mark and quality level for unencapsulated devices (die). The quality level designators for unencapsulated devices (die) that are applicable for this specification sheet from the lowest to the highest level are as follows: "JANHC" and "JANKC".
- * 1.5.3 Radiation hardness assurance (RHA) designator. The RHA levels that are applicable for this specification sheet from lowest to highest are as follows: "M", "D", "P", "L", "R", "F", "G", and "H".
- * 1.5.4 Device type. The designation system for the device types of transistors covered by this specification sheet are as follows.
- * 1.5.4.1 First number and first letter symbols. The transistors of this specification sheet use the first number and letter symbols "2N".
- * 1.5.4.2 Second number symbols. The second number symbols for the transistors covered by this specification sheet are as follows: "3810" and "3811".
- * 1.5.4.3 Suffix letters/symbols. The suffix letter "L" is used on devices that are packaged in the TO-78 package of figure 1 that have a long lead length: 1.500 inches (38.10 mm) minimum and 1.750 inches (44.45 mm) maximum. Devices with standard length leads (see figure 1, TO-78) use no suffix. The suffix letter "U" is used on devices that are packaged in the surface mount package of figure 2.
- * 1.5.5 Lead finish. The lead finishes applicable to this specification sheet are listed on QML-19500.
- * 1.5.6 Die identifiers for unencapsulated devices (manufacturers and critical interface identifiers). The manufacturer die identifier that is applicable for this specification sheet is "A" (see figure 3) and "B" (see figure 4).

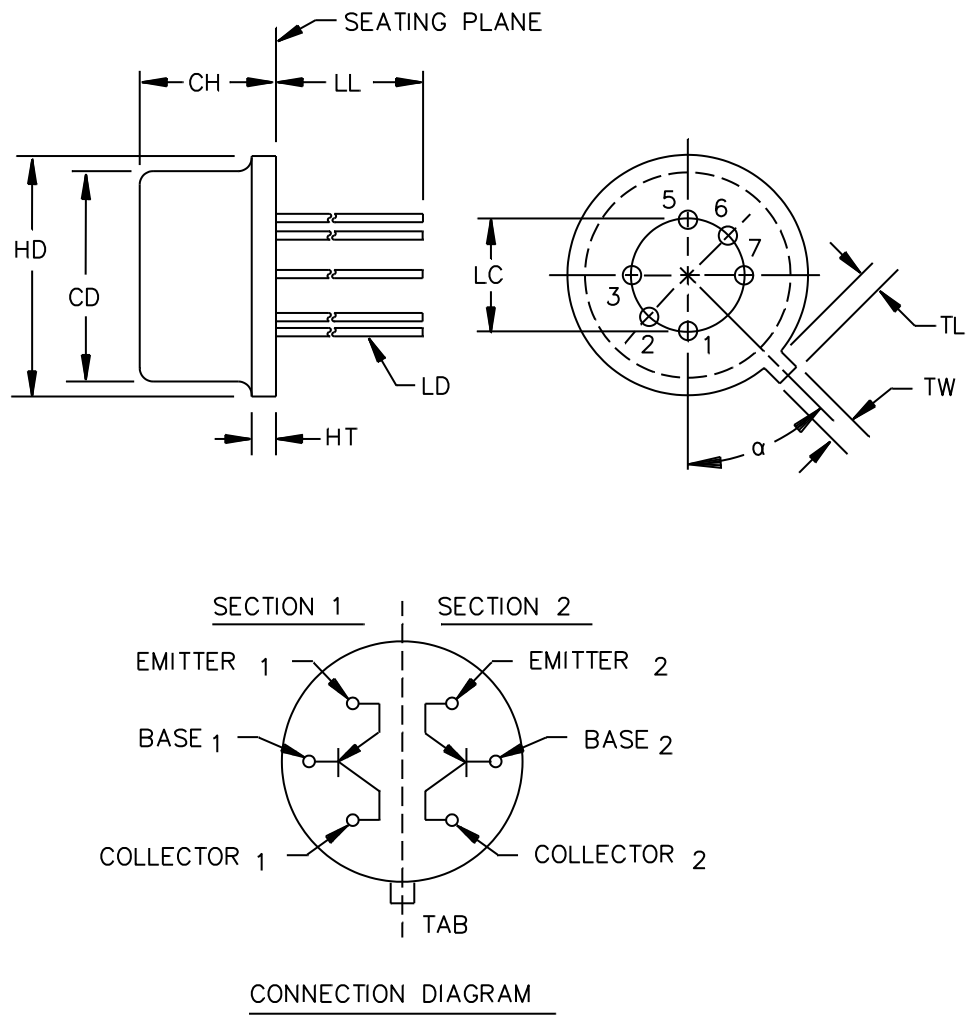


FIGURE 1. Physical dimensions (similar to TO-78).

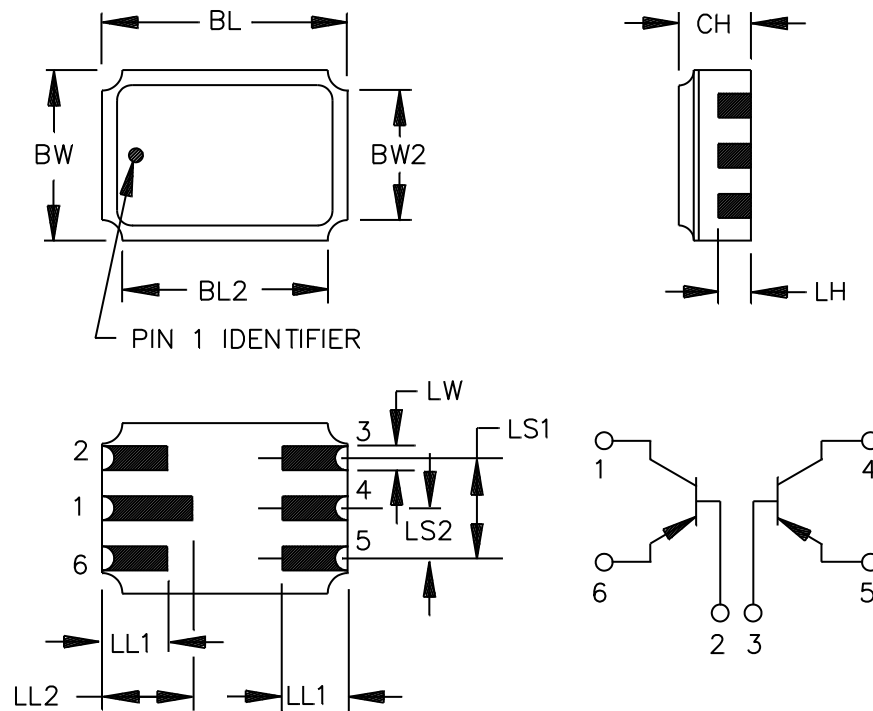
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LTR	Dimensions				Notes
	Inches		Millimeters		
	Min	Max	Min	Max	
CD	.305	.335	7.75	8.51	
CH	.150	.185	3.81	4.70	
HD	.335	.370	8.51	9.40	
HT	.009	.041	0.23	1.04	
LC	.200 BSC		5.08 BSC		
LD	.016	.021	0.41	0.53	10
LL	See notes 10, 11, and 13				
α	45°TP		45°TP		9
TL	.029	.045	0.74	1.14	5, 6
TW	.028	.034	0.71	0.86	4, 5

NOTES:

1. Dimensions are in inches.
2. Millimeters are given for general information only.
3. Refer to rules for dimensioning Semiconductor Product Outlines included in Publication No. 95.
4. Lead number 4 and 8 omitted on this variation.
5. TW must be held to a minimum length of .021 inch (0.53 mm).
6. LL measured from maximum HD.
7. Details of outline in this zone optional.
8. CD shall not vary more than .010 inch (0.25mm) in zone P. This zone is controlled for automatic handling.
9. Leads at gauge plane .054 - .055 inch (1.37 - 1.40 mm) below seating plane shall be within .007 (0.18 mm) radius of true position (TP) at a maximum material condition (MMC) relative to the tab at MMC. The device may be measured by direct methods or by the gauge and gauging procedure described on gauge drawing GS-1.
10. LD applies to LL minimum.
11. r (radius) applies to both inside corners of tab.
12. For transistor types 2N3810 and 2N3811, LL is .500 inch (12.70 mm) minimum, and .750 inch (19.05 mm) maximum. (TO-99).
13. For transistor types 2N3810L and 2N3811L, LL is 1.500 inches (38.10 mm) minimum, and 1.750 inches (44.45 mm) maximum.
14. In accordance with AMSE Y14.5M, diameters are equivalent to ϕ x symbology.
15. Leads 3 and 5 = emitter, leads 2 and 6 = base, leads 1 and 7 = collector.

FIGURE 1. Physical dimensions (similar to TO-78) - Continued.



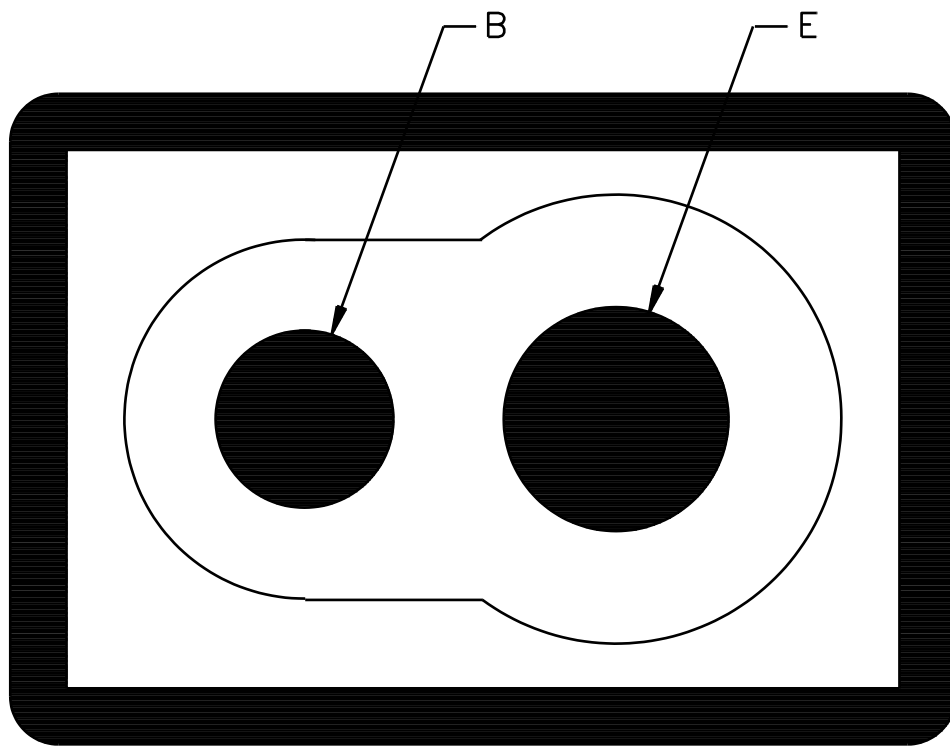
Symbol	Dimensions			
	Inches		Millimeters	
	Min	Max	Min	Max
BL	.240	.250	6.10	6.35
BL2		.250		6.35
BW	.165	.175	4.19	4.45
BW2		.175		4.45
CH	.044	.080	1.12	2.03
LH	.026	.039	0.66	0.99
LL1	.060	.070	1.52	1.78
LL2	.082	.098	2.08	2.49
LS1	.095	.105	2.41	2.67
LS2	.045	.055	1.14	1.40
LW	.022	.028	0.56	0.71

Pin no.	Transistor
1	Collector no. 1
2	Base no. 1
3	Base no. 2
4	Collector no. 2
5	Emitter no. 2
6	Emitter no. 1

NOTES:

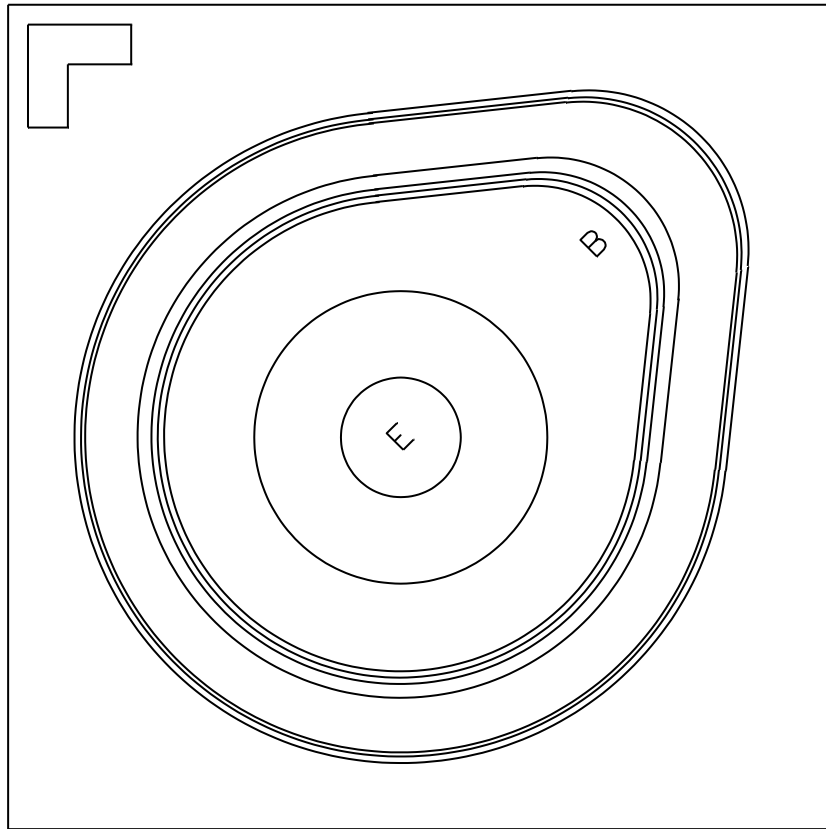
1. Dimensions are in inches.
2. Millimeters are given for general information only.
3. In accordance with AMSE Y14.5M, diameters are equivalent to ϕ x symbology.

FIGURE 2. Physical dimensions (2N3810U and 2N3811U).



1. Chip size..... .015 x .019 inch \pm .001 inch (0.38 x 0.48 mm \pm 0.025 mm).
2. Chip thickness..... .010 \pm 0.0015 inch (0.25 \pm 0.038 mm).
3. Top metal..... Aluminum 15,000 Å minimum, 18,000 Å nominal.
4. Back metal..... A. Gold 3,000 Å minimum, 5,000 Å nominal.
5. Backside..... Collector.
6. Bonding pad..... B = .003 inch (0.07 mm), E = .004 inch (0.10 mm) diameter.
7. Passivation..... Si₃N₄ (Silicon Nitride) 5,600 Å minimum, 8,000 Å nominal.

FIGURE 3. JANHC and JANKC A-version die dimensions.



Die size:	.018 x .018 inch (0.457 X 0.457 mm).
Die thickness:	.008 ±.0016 inch (0.20 ±0.041 mm).
Base pad:	.0025 inch diameter (0.064 mm).
Emitter pad:	.003 inch diameter (0.076 mm).
Back metal:	Gold, 6,500 ±1,950 Å.
Top metal:	Aluminum, 19,500 ±2,500 Å.
Back side:	Collector.
Glassivation:	SiO ₂ , 7,500 ±1,500 Å.

FIGURE 4. JANHNC and JANKC B-version die dimensions.

2. APPLICABLE DOCUMENTS

- * 2.1 General. The documents listed in this section are specified in sections 3 and 4 of this specification. This section does not include documents cited in other sections of this specification or recommended for additional information or as examples. While every effort has been made to ensure the completeness of this list, document users are cautioned that they must meet all specified requirements of documents cited in sections 3 and 4 of this specification, whether or not they are listed.

2.2 Government documents.

2.2.1 Specifications, standards, and handbooks. The following specifications, standards, and handbooks form a part of this document to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

DEPARTMENT OF DEFENSE SPECIFICATIONS

MIL-PRF-19500 - Semiconductor Devices, General Specification for.

DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-750 - Test Methods for Semiconductor Devices.

- * (Copies of these documents are available online at <http://quicksearch.dla.mil/>).

2.3 Order of precedence. Unless otherwise noted herein or in the contract, in the event of a conflict between the text of this document and the references cited herein, the text of this document takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

3.1 General. The individual item requirements shall be as specified in **MIL-PRF-19500** and as modified herein.

3.2 Qualification. Devices furnished under this specification shall be products that are manufactured by a manufacturer authorized by the qualifying activity for listing on the applicable qualified manufacturers list before contract award (see 4.2 and 6.3).

3.3 Abbreviations, symbols, and definitions. Abbreviations, symbols, and definitions used herein shall be as specified in **MIL-PRF-19500** and as follows.

H_{FE3-1}	-----	-Static forward-current-gain-ratio. The matching ratio of the static forward-current transfer ratios of each section.
h_{FE3-2}		
$ V_{BE1} - V_{BE2} $	-----	-Absolute value of base-emitter-voltage differential between the individual sections.
$ \Delta V_{BE1-2}(T1) - \Delta V_{BE1-2}(T2) $	-----	- Absolute value of the algebraic difference between the base-emitter-voltage differentials between the individual sections at two different temperatures.

3.4 Interface and physical dimensions. The interface and physical dimensions shall be as specified in **MIL-PRF-19500**, and on [figure 1](#) (similar to TO-78), [figure 2](#) (for U devices) and [figures 3](#) and [4](#) for unencapsulated devices.

3.4.1 Lead finish. Lead finish shall be solderable in accordance with **MIL-PRF-19500**, **MIL-STD-750**, and herein. Where a choice of lead finish is desired, it shall be specified in the acquisition document (see 6.2).

3.5 Radiation hardness assurance (RHA). Radiation hardness assurance requirements, PIN designators, and test levels shall be as defined in [MIL-PRF-19500](#).

3.6 Electrical performance characteristics. Unless otherwise specified herein, the electrical performance characteristics are as specified in [1.3](#), [1.4](#), [1.5](#), and [table I](#).

3.7 Electrical test requirements. The electrical test requirements shall be as specified in [table I](#).

3.8 Marking. Marking shall be in accordance with [MIL-PRF-19500](#). The radiation hardened designator M, D, P, L, R, F, G, or H shall immediately precede (or replace) the device "2N" identifier (depending upon degree of abbreviation required).

3.9 Workmanship. Transistors shall be processed in such a manner as to be uniform in quality and shall be free from other defects that will affect life, serviceability, or appearance.

4. VERIFICATION

4.1 Classification of inspections. The inspection requirements specified herein are classified as follows:

- a. Qualification inspection (see [4.2](#)).
- b. Screening (see [4.3](#)).
- c. Conformance inspection (see [4.4](#) and [tables I, II, and III](#)).

4.2 Qualification inspection. Qualification inspection shall be in accordance with [MIL-PRF-19500](#) and as specified herein.

4.2.1 JANHC and JANKC qualification. JANHC and JANKC qualification inspection shall be in accordance with [MIL-PRF-19500](#).

4.2.2 Group E qualification. Group E inspection shall be performed for qualification or re-qualification only. In case qualification was awarded to a prior revision of the specification sheet that did not request the performance of [table III](#) tests, the tests specified in [table III](#) herein that were not performed in the prior revision shall be performed on the first inspection lot of this revision to maintain qualification.

4.2.2.1 Group E thermal response. With extremely small junction devices such as this one, a true thermal impedance cannot be measured, only calculated. While "thermal response" has been substituted for "thermal impedance" herein, the terms, units and procedure as essentially unchanged. Each supplier shall submit a thermal response ($Z_{\theta JX}$) histogram of the entire qualification lot. The histogram data shall be taken prior to the removal of devices that are atypical for thermal response. Thermal response curves (from $Z_{\theta JX}$ test pulse time to $R_{\theta JX}$ minimum steady-state time) of the best device in the qual lot and the worst device in the qual lot (that meets the supplier proposed screening limit), or from the thermal grouping, shall be submitted. The optimal test conditions and proposed initial thermal response screening limit shall be provided in the qualification report. Data indicating how the optimal test conditions were derived for $Z_{\theta JX}$ shall also be submitted. The proposed maximum thermal response $Z_{\theta JX}$ screening limit shall be submitted. The qualifying activity may approve a different $Z_{\theta JX}$ limit for conformance inspection end-point measurements as applicable. Equivalent data, procedures, or statistical process control plans may be used for part, or all, of the above requirements. The approved thermal response conditions and limit for $Z_{\theta JX}$ shall be used by the supplier in screening and [table I](#), subgroup 2. The approved thermal resistance conditions for $R_{\theta JX}$ shall be used by the supplier for conformance inspection. For product families with similar thermal characteristics based on the same physical and thermal die, package, and construction combination (thermal grouping), the supplier may use the same thermal response curves.

* 4.3 Screening.

- * 4.3.1 Screening (JANS, JANTX, and JANTXV levels only). Screening of packaged devices shall be in accordance with table E-IV of [MIL-PRF-19500](#), and as specified herein. The following measurements shall be made in accordance with [table I](#) herein. Devices that exceed the limits of [table I](#) herein shall not be acceptable.

Screen (see table E-IV of MIL-PRF-19500)	Measurement	
	JANS level	JANTX and JANTXV levels
(1) 3c	Thermal response, method 3131 of MIL-STD-750 . See 4.3.2 .	Thermal response, method 3131 of MIL-STD-750 . See 4.3.2 .
9	I_{CBO2} , h_{FE4}	Not applicable
10	24 hours minimum	24 hours minimum
11	I_{CBO2} , h_{FE4} ; ΔI_{CBO2} = 100 percent of initial value or 5 nA dc, whichever is greater. Δh_{FE4} = ± 15 percent.	I_{CBO2} , h_{FE4}
12	See 4.3.2	See 4.3.2
13	Subgroups 2 and 3 of table I herein; ΔI_{CBO2} = 100 percent of initial value or 5 nA dc, whichever is greater; Δh_{FE4} = ± 15 percent.	Subgroup 2 and the base emitter voltage (non-saturated) (absolute value of differential-change with temperature) tests of subgroup 3 of table I herein; ΔI_{CBO2} = 100 percent of initial value or 5 nA dc, whichever is greater; Δh_{FE4} = ± 15 percent.

- (1) Shall be performed anytime after temperature cycling, screen 3a; JANTX and JANTXV do not need to be repeated in screening requirements.

4.3.2 Power burn-in conditions. Power burn-in conditions are as follows: V_{CB} = 10 - 30 V dc. Power shall be applied to achieve T_J = 135°C minimum and using a minimum P_D = 75 percent of P_T maximum rated as defined in [1.3](#). With approval of the qualifying activity and preparing activity, alternate burn-in criteria (hours, bias conditions, T_J , and mounting conditions) may be used for JANTX and JANTXV quality levels. A justification demonstrating equivalence is required. In addition, the manufacturing site's burn-in data and performance history will be essential criteria for burn-in modification approval.

4.3.2 Thermal response. For very small junction devices, such as this, the term "thermal response" shall be used in lieu of "thermal impedance" although measurements shall be performed the same way as thermal impedance in accordance with method 3131 of [MIL-STD-750](#) using the guidelines in that method for determining I_M , I_H , t_H , t_{SW} (V_C and V_H where appropriate). Measurement delay time (t_{MD}) = 70 μ s max. See group E, subgroup 4 herein.

- * 4.3.3 Screening of unencapsulated die (JANHC and JANKC). Screening of JANHC and JANKC unencapsulated die shall be in accordance with appendix G of [MIL-PRF-19500](#).

4.4 Conformance inspection. Conformance inspection shall be in accordance with [MIL-PRF-19500](#), and as specified herein. If alternate screening is being performed in accordance with [MIL-PRF-19500](#), a sample of screened devices shall be submitted to and pass the requirements of subgroup 1 and 2, of [table I](#) herein, inspection only (table E-VIB, group B, subgroup 1 is not required to be performed since solderability and resistance to solvents testing is performed in A1 herein).

4.4.1 Group A inspection. Group A inspection shall be conducted in accordance with MIL-PRF-19500 and table I herein.

- * 4.4.2 Group B inspection. Group B inspection shall be conducted in accordance with the tests and conditions specified for subgroup testing in table E-VIA (JANS) of MIL-PRF-19500 and 4.4.2.1. Delta requirements shall be in accordance with 4.5.3 herein. See 4.4.2.2 for JAN, JANTX, and JANTXV group B testing. Electrical measurements (end-points) and delta requirements for JAN, JANTX, and JANTXV shall be after each step in 4.4.2.2 and shall be in accordance with table I, subgroup 2 and 4.5.3 herein.

4.4.2.1 Group B inspection (JANS), table E-VIA of MIL-PRF-19500.

Subgroup	Method	Condition
B4	1037	$V_{CB} = 10$ V dc, adjust device current, or power, to achieve a minimum ΔT_J of $+100^\circ\text{C}$.
B5	1027	$V_{CB} = 10$ V dc; $P_D \geq 100$ percent of maximum rated P_T (see 1.3). (NOTE: If a failure occurs, resubmission shall be at the test conditions of the original sample.) Option 1: 96 hours minimum sample size in accordance with MIL-PRF-19500, table E-Via, adjust T_A or P_D to achieve $T_J = +275^\circ\text{C}$ minimum. Option 2: 216 hours minimum, sample size = 45, $c = 0$; adjust T_A or P_D to achieve a $T_J = +225^\circ\text{C}$ minimum.

4.4.2.2 Group B inspection, (JAN, JANTX, and JANTXV). Separate samples may be used for each step. In the event of a lot failure, the resubmission requirements of MIL-PRF-19500 shall apply. In addition, all catastrophic failures during CI shall be analyzed to the extent possible to identify root cause and corrective action.

Step	Method	Condition
1	1026	Steady-state life: 1,000 hours minimum, $V_{CB} = 10$ V dc, power shall be applied to achieve $T_J = +150^\circ\text{C}$ minimum using a minimum of $P_D = 75$ percent of maximum rated P_T as defined in 1.3. $n = 45$ devices, $c = 0$. The sample size may be increased and the test time decreased as long as the devices are stressed for a total of 45,000 device hours minimum, and the actual time of test is at least 340 hours.
2	1048	Blocking life, $T_A = +150^\circ\text{C}$, $V_{CB} = 80$ percent of rated voltage, 48 hours minimum. $n = 45$ devices, $c = 0$.
3	1032	High-temperature life (non-operating), $t = 340$ hours, $T_A = +200^\circ\text{C}$. $n = 22$, $c = 0$.

4.4.2.3 Group B sample selection. Samples selected from group B inspection shall meet all of the following requirements:

- For JAN, JANTX, and JANTXV samples shall be selected randomly from a minimum of three wafers (or from each wafer in the lot) from each wafer lot. For JANS, samples shall be selected from each inspection lot. See MIL-PRF-19500.
- Shall be chosen from an inspection lot that has been submitted to and passed table I, subgroup 2, conformance inspection. When the final lead finish is solder or any plating prone to oxidation at high temperature, the samples for life test (subgroups B4 and B5 for JANS, and group B for JAN, JANTX, and JANTXV) may be pulled prior to the application of final lead finish.

- * 4.4.3 Group C inspection. Group C inspection shall be conducted in accordance with the conditions specified for subgroup testing in table E-VII of [MIL-PRF-19500](#), and in 4.4.3.1 (JANS) and 4.4.3.2 (JAN, JANTX, and JANTXV) herein for group C testing. Delta requirements shall be in accordance with 4.5.3 herein.

4.4.3.1 Group C inspection (JANS), table E-VII of [MIL-PRF-19500](#).

<u>Subgroup</u>	<u>Method</u>	<u>Condition</u>
C2	2036	Test condition E; (not applicable for U devices).
C5	3131	$R_{\theta JA}$ and $R_{\theta JC}$ only, as applicable (see 1.3) and 4.3.3 herein.
C6	1026	1,000 hours at $V_{CB} = 10$ V dc; power shall be applied to achieve $T_J = +150^\circ\text{C}$ minimum and a minimum of $P_D = 75$ percent of maximum rated P_T as defined in 1.3, $n = 45$, $c = 0$. The sample size may be increased and the test time decreased as long as the devices are stressed for a total of 45,000 device hours minimum, and the actual time of test is at least 340 hours.

4.4.3.2 Group C inspection (JAN, JANTX, and JANTXV), table E-VII of [MIL-PRF-19500](#).

<u>Subgroup</u>	<u>Method</u>	<u>Condition</u>
C2	2036	Test condition E; not applicable for U device.
C5	3131	$R_{\theta JA}$ and $R_{\theta JC}$ only, as applicable (see 1.3) and 4.3.3 herein.
C6		Not applicable.

4.4.3.3 Group C sample selection. Samples for subgroups in group C shall be chosen at random from any inspection lot containing the intended package type and lead finish procured to the same specification which is submitted to and passes [table I](#) tests herein for conformance inspection. When the final lead finish is solder or any plating prone to oxidation at high temperature, the samples for C6 life test may be pulled prior to the application of final lead finish. Testing of a subgroup using a single device type enclosed in the intended package type shall be considered as complying with the requirements for that subgroup.

4.4.4 Group D inspection. Conformance inspection for hardness assured JANS, and JANTXV types shall include the group D tests specified in [table II](#) herein. These tests shall be performed as required in accordance with [MIL-PRF-19500](#) and method 1019 of [MIL-STD-750](#), for total ionizing dose or method 1017 of [MIL-STD-750](#) for neutron fluence as applicable (see 6.2 herein), except group D, subgroup 2 may be performed separate from other subgroups. Alternate package options may also be substituted for the testing provided there is no adverse effect to the fluence profile or to the total dose response from molecular hydrogen in the package. Any alternate package should be tested for molecular hydrogen using method 1018 of [MIL-STD-750](#). If hydrogen is detected, total dose testing shall be performed in the alternate package.

4.4.5 Group E inspection. Group E inspection shall be conducted in accordance with the conditions specified for subgroup testing in table E-IX of [MIL-PRF-19500](#) and as specified in [table III](#) herein. Electrical measurements (end-points) shall be in accordance with [table I](#), subgroup 2 herein; delta measurements shall be in accordance with the applicable steps of 4.5.3.

4.5 Methods of inspection. Methods of inspection shall be as specified in the appropriate tables and as follows.

4.5.1 Testing of units. All specified electrical tests, including electrical measurements (end-points) and delta requirement tests, shall be performed equally on both sections of the transistor types covered herein, except where the electrical characteristic being evaluated applies to the transistor as a device entity.

4.5.2 Pulse measurements. Conditions for pulse measurement shall be as specified in section 4 of [MIL-STD-750](#).

4.5.3 Delta requirements. Delta requirements shall be as specified below:

Step	Inspection	MIL-STD-750		Symbol	Limit	Unit
		Method	Conditions			
1	Collector-base cutoff current	3036	Bias condition D, $V_{CB} = 50 \text{ V dc}$	$\Delta I_{CB02} (1)$	100 percent of initial value or 8 nA dc, whichever is greater.	
2	Forward current transfer ratio	3076	$V_{CE} = 5 \text{ V dc}$; $I_C = 1 \text{ mA dc}$; pulsed see 4.5.2	$\Delta h_{FE4} (1)$	± 25 percent change from initial reading.	

(1) Devices which exceed the [table I](#) limits for this test shall not be accepted.

4.5.4 Disposition of leads when testing characteristics of each section. During the measurement of the characteristic of each section, the leads of the section not under test shall be open-circuited.

4.5.5 Forward-current-gain ratio. The value for the forward-current-gain ratio for each individual section of a dual unit shall be measured using method 3076 of [MIL-STD-750](#). The forward-current-gain ratio shall be calculated by dividing one of the values by the other. If possible, this ratio shall be measured directly to improve accuracy.

4.5.6 Base-emitter-voltage differential. The base-emitter-voltage differential shall be determined by connecting the emitters of the individual sections together, applying specified electrical test conditions to each individual section in accordance with method 3066 of [MIL-STD-750](#), test condition B and measuring the absolute value of the voltage between the bases of the individual sections of a dual unit.

4.5.7 Base-emitter-voltage differential change with temperature. The value of the base-emitter-voltage differential shall be measured at the two specified temperatures in accordance with [4.5.6](#) except that the identities of the individual sections shall be maintained. The absolute value of the algebraic difference between the values at the two temperature extremes shall be calculated. A mathematical formula for this parameter is:

$$|(V_{BE1} - V_{BE2}) T1 - (V_{BE1} - V_{BE2}) T2|$$

4.5.8 Noise figure test. Noise figure shall be measured using a model No. 2173C/2181 Quan Tech Laboratories test set, or equivalent. Conditions shall be as specified in [table I](#).

4.5.9 Noise figure (wideband) test. Wideband noise figure shall be measured using a model No. 512 Quan Tech Laboratories test set, or equivalent. Conditions shall be as specified in [table I](#).

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TABLE I. Group A inspection.

Inspection <u>1/</u>	MIL-STD-750		Symbol	Limit		Unit
	Method	Conditions		Min	Max	
<u>Subgroup 1</u> <u>2/</u>						
Visual and mechanical examination <u>3/</u>	2071					
Solderability <u>2/</u> <u>3/</u> <u>4/</u>	2026	n = 15 leads, c = 0				
Resistance to solvents <u>3/</u> <u>4/</u> <u>5/</u>	1022	n = 15 devices, c = 0				
* Salt atmosphere	1041	(Laser marked devices only) n = 6 devices, c = 0.				
Temp cycling <u>2/</u> <u>3/</u> <u>4/</u>	1051	Test condition C, 25 cycles. n = 22 devices, c = 0				
Hermetic seal <u>4/</u> <u>6/</u> Fine leak Gross leak	1071	n = 22 devices, c = 0				
Electrical measurements <u>4/</u>		Table I , subgroup 2				
Bond strength <u>2/</u> <u>3/</u> <u>4/</u>	2037	Precondition T _A = +250°C at t = 24 hours or T _A = +300°C at t = 2 hours n = 11 wires, c = 0				
Decap internal visual (design verification)	2075	n = 4 devices, c = 0				
<u>Subgroup 2</u>						
Thermal response	3131	See 4.3.3 .	Z _{θJX}			°C/W
Collector to base cutoff current	3036	Bias condition D, V _{CB} = 60 V dc (see 4.5.2)	I _{CBO1}		10	μA dc
Breakdown voltage, collector to emitter	3011	Bias condition D; I _C = 100 μA dc; pulsed (see 4.5.2)	V _{(BR)CEO}	60		V dc
Emitter to base cutoff current	3061	Bias condition D, V _{EB} = 5 V dc	I _{EBO1}		10	μA dc
Collector to base cutoff current	3036	Bias condition D, V _{CB} = 50 V dc	I _{CBO2}		10	nA dc
Emitter to base cutoff current	3061	Bias condition D, V _{EB} = 4 V dc	I _{EBO2}		10	nA dc
Forward-current transfer ratio 2N3811, 2N3811L, U only	3076	V _{CE} = 5 V dc; I _C = 1 μA dc	h _{FE1}	75		

See footnotes at end of table.

TABLE I. Group A inspection - Continued.

Inspection <u>1</u> /	MIL-STD-750		Symbol	Limit		Unit
	Method	Conditions		Min	Max	
<u>Subgroup 2</u> - Continued						
Forward-current transfer ratio 2N3810, 2N3810L, U 2N3811, 2N3811L, U	3076	V _{CE} = 5 V dc; I _C = 10 μA dc	h _{FE2}	100 225		
Forward-current transfer ratio 2N3810, 2N3810L, U 2N3811, 2N3811L, U	3076	V _{CE} = 5 V dc; I _C = 100 μA dc	h _{FE3}	150 300	450 900	
Forward-current transfer ratio 2N3810, 2N3810L, U 2N3811, 2N3811L, U	3076	V _{CE} = 5 V dc; I _C = 1 mA dc	h _{FE4}	150 300	450 900	
Forward-current transfer ratio 2N3810, 2N3810L, U 2N3811, 2N3811L, U	3076	V _{CE} = 5 V dc; I _C = 10 mA dc	h _{FE5}	125 250		
Collector to emitter voltage (saturated)	3071	I _C = 100 μA dc, I _B = 10 μA dc	V _{CE(sat)1}		0.2	V dc
Collector to emitter voltage (saturated)	3071	I _C = 1 mA dc, I _B = 100 μA dc	V _{CE(sat)2}		0.25	V dc
Base-emitter voltage (saturated)	3066	Test condition A; I _C = 100 μA dc, I _B = 10 μA dc	V _{BE(sat)1}		0.7	V dc
Base-emitter voltage (saturated)	3066	Test condition A; I _C = 1 mA dc, I _B = 100 μA dc	V _{BE(sat)2}		0.8	V dc
Base-emitter voltage (nonsaturated)	3066	Test condition B; V _{CE} = 5 V dc; I _C = 100 μA dc	V _{BE(ON)}		0.7	V dc
Forward-current transfer ratio (gain ratio)	3076	V _{CE} = 5 V dc; I _C = 100 μA dc (see 4.5.5)	h _{FE3-1} / h _{FE3-2}	0.9	1.11	
Base emitter voltage (nonsaturated) (absolute value of differential) <u>7</u> /	3066	Test condition B V _{CE} = 5 V dc; I _C = 10 μA dc (see 4.5.6)	V _{BE1} - V _{BE2} 1		5	mV dc
Base emitter voltage (nonsaturated) (absolute value of differential) <u>7</u> /	3066	Test condition B V _{CE} = 5 V dc; I _C = 100 μA dc (see 4.5.6)	V _{BE1} - V _{BE2} 2		3	mV dc

See footnotes at end of table.

TABLE I. Group A inspection - Continued.

Inspection 1/	MIL-STD-750		Symbol	Limit		Unit
	Method	Conditions		Min	Max	
<u>Subgroup 2</u> - Continued						
Base emitter voltage (nonsaturated) (absolute value of differential) 7/	3066	Test condition B $V_{CE} = 5$ V dc; $I_C = 10$ mA dc (see 4.5.6)	$ V_{BE1} - V_{BE2} 3$		5	mV dc
<u>Subgroup 3</u>						
High temperature operation:		$T_A = +150^{\circ}\text{C}$				
Base emitter voltage (absolute value of differential-change with temperature)	3066	Test condition B $V_{CE} = 5$ V dc; $I_C = 100$ μA dc $T_A = +125^{\circ}\text{C}$ and $+25^{\circ}\text{C}$ (see 4.5.7)	$ \Delta V_{BE1} - V_{BE2} \Delta T_A 2$		1.0	mV dc
Collector to base cutoff current	3036	Bias condition D, $V_{CB} = 50$ V dc	I_{CBO3}		10	μA dc
Low-temperature operation:		$T_A = -55^{\circ}\text{C}$				
Forward-current transfer ratio	3076	$V_{CE} = 5$ V dc; $I_C = 100$ μA dc	h_{FE6}			
2N3810, 2N3810L, U 2N3811, 2N3811L, U				60 100		
Base emitter voltage (absolute value of differential-change with temperature)	3066	Test condition B $V_{CE} = 5$ V dc; $I_C = 100$ μA dc $T_A = +25^{\circ}\text{C}$ and -55°C (see 4.5.7)	$ \Delta V_{BE1} - V_{BE2} \Delta T_A 1$		0.8	mV dc
<u>Subgroup 4</u>						
Open circuit output capacitance	3236	$V_{CB} = 5$ V dc; $I_E = 0$; $100 \text{ kHz} \leq f \leq 1 \text{ MHz}$	C_{obo}		5	pF
Input capacitance (output open-circuited)	3240	$V_{EB} = 0.5$ V dc; $I_C = 0$; $100 \text{ kHz} \leq f \leq 1 \text{ MHz}$	C_{ibo}		8	pF
Magnitude of small-signal short-circuit forward-current transfer ratio	3306	$V_{CE} = 5$ V dc; $I_C = 500$ μA dc $f = 30 \text{ MHz}$	$ h_{FE} 1$	1.0		
Magnitude of small-signal short-circuit forward-current transfer ratio	3306	$V_{CE} = 5$ V dc; $I_C = 1$ mA dc $f = 100 \text{ MHz}$	$ h_{FE} 2$	1.0	5	

See footnotes at end of table.

TABLE I. Group A inspection - Continued.

Inspection 1/	MIL-STD-750		Symbol	Limit		Unit
	Method	Conditions		Min	Max	
<u>Subgroup 4</u> - Continued						
Small-signal short- circuit forward current transfer ratio 2N3810, 2N3810L, U 2N3811, 2N3811L, U	3206	V _{CE} = 10 V dc; I _C = 1 mA dc f = 1 kHz	h _{fe}	150 300	600 900	
Small-signal short-circuit input impedance 2N3810, 2N3810L, U 2N3811, 2N3811L, U	3201	V _{CE} = 10 V dc; I _C = 1 mA dc; f = 1 kHz	h _{ie}	3 3	30 40	kΩ kΩ
Small-signal open-circuit output admittance	3216	V _{CE} = 10 V dc; I _C = 1 mA dc; f = 1 kHz	h _{oe}	5	60	μmhos
Small-signal open-circuit reverse-voltage transfer ratio	3211	V _{CE} = 10 V dc; I _C = 1 mA dc; f = 1 kHz	h _{re}		25x10 ⁻⁴	
Noise figure 2N3810, 2N3810L, U 2N3811, 2N3811L, U	3246	V _{CE} = 10 V dc; I _C = 100 μA dc; R _g = 3 kΩ, f = 100 Hz (see 4.5.8)	F1		7 4	dB dB
Noise figure 2N3810, 2N3810L, U 2N3811, 2N3811L, U	3246	V _{CE} = 10 V dc; I _C = 100 μA dc; R _g = 3 kΩ, f = 1 kHz (see 4.5.8)	F2		3 1.5	dB dB
Noise figure 2N3810, 2N3810L, U 2N3811, 2N3811L, U	3246	V _{CE} = 10 V dc; I _C = 100 μA dc; R _g = 3 kΩ, f = 10 kHz (see 4.5.8)	F3		2.5 2.0	dB dB
Noise figure (wideband) 2N3810, 2N3810L, U 2N3811, 2N3811L, U	3246	V _{CE} = 10 V dc; I _C = 100 μA dc; R _g = 3 kΩ, noise bandwidth 10 Hz to 15.7 kHz (see 4.5.9)	F1		3.5 2.5	dB dB
<u>Subgroup 5 and 6</u>						
Not applicable						

1/ For sampling plan see MIL-PRF-19500.

2/ For resubmission of failed test in subgroup 1 of table I, double the sample size of the failed test or sequence of tests. A failure in table I, subgroup 1 shall not require retest of the entire subgroup. Only the failed test shall be rerun upon submission.

3/ Separate samples may be used.

4/ Not required for JANS devices.

5/ Not required for laser marked devices.

6/ This hermetic seal test is an end-point to temp-cycling in addition to electrical measurements.

7/ When using table I, subgroup 2, as electrical end-points, this test is only required for JANS end-points, except subgroups C2 and C3.

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TABLE II. Group D inspection.

Inspection <u>1/</u> <u>2/</u> <u>3/</u>	MIL-STD-750		Symbol	Limit		Unit
	Method	Conditions		Min	Max	
<u>Subgroup 1 4/</u>						
Neutron irradiation	1017	Neutron exposure $V_{CES} = 0V$				
Collector to base cutoff current	3036	Bias condition D; $V_{CB} = 60 V$ dc	I_{CBO1}		20	μA dc
Breakdown voltage, collector to emitter	3011	Bias condition D; $I_C = 100 \mu A$ dc; pulsed (see 4.5.2)	$V_{(BR)CEO}$	60		V dc
Emitter to base cutoff current	3061	Bias condition D, $V_{EB} = 5 V$ dc	I_{EBO1}		20	μA dc
Collector to base cutoff current	3036	Bias condition D, $V_{CB} = 50 V$ dc	I_{CBO2}		20	nA dc
Emitter to base cutoff current	3061	Bias condition D, $V_{EB} = 4 V$ dc	I_{EBO2}		20	nA dc
Forward-current transfer ratio 2N3811, 2N3811L, U only	3076	$V_{CE} = 5 V$ dc; $I_C = 1 \mu A$ dc	$[h_{FE1}]$ <u>5/</u>	[37.5]		
Forward-current transfer ratio 2N3810, 2N3810L, U 2N3811, 2N3811L, U	3076	$V_{CE} = 5 V$ dc; $I_C = 10 \mu A$ dc	$[h_{FE2}]$ <u>5/</u>	[50] [112.5]		
Forward-current transfer ratio 2N3810, 2N3810L, U 2N3811, 2N3811L, U	3076	$V_{CE} = 5 V$ dc; $I_C = 100 \mu A$ dc	$[h_{FE3}]$ <u>5/</u>	[75] [150]	450 900	
Forward-current transfer ratio 2N3810, 2N3810L, U 2N3811, 2N3811L, U	3076	$V_{CE} = 5 V$ dc; $I_C = 1 mA$ dc	$[h_{FE4}]$ <u>5/</u>	[75] [150]	450 900	
Forward-current transfer ratio 2N3810, 2N3810L, U 2N3811, 2N3811L, U	3076	$V_{CE} = 5 V$ dc; $I_C = 10 mA$ dc	$[h_{FE5}]$ <u>5/</u>	[62.5] [125]		
Collector to emitter voltage (saturated)	3071	$I_C = 100 \mu A$ dc, $I_B = 10 \mu A$ dc	$V_{CE(sat)1}$		0.23	V dc
Collector to emitter voltage (saturated)	3071	$I_C = 1 mA$ dc, $I_B = 100 \mu A$ dc	$V_{CE(sat)2}$		0.29	V dc
Base-emitter voltage (saturated)	3066	Test condition A; $I_C = 100 \mu A$ dc, $I_B = 10 \mu A$ dc	$V_{BE(sat)1}$		0.81	V dc
Base-emitter voltage (saturated)	3066	Test condition A; $I_C = 1 mA$ dc, $I_B = 100 \mu A$ dc	$V_{BE(sat)2}$		0.92	V dc

See footnotes at end of table.

TABLE II. Group D inspection - Continued.

Inspection <u>1/</u> <u>2/</u> <u>3/</u>	MIL-STD-750		Symbol	Limit		Unit
	Method	Conditions		Min	Max	
Subgroup 1 - Continued						
Base-emitter voltage (nonsaturated)	3066	Test condition B; $V_{CE} = 5 \text{ V dc}$; $I_C = 100 \text{ }\mu\text{A dc}$	$V_{BE(ON)}$		0.81	V dc
Forward-current transfer ratio (gain ratio)	3076	$V_{CE} = 5 \text{ V dc}$; $I_C = 100 \text{ }\mu\text{A dc}$ (see 4.5.5)	h_{FE3-1} / h_{FE3-2}	0.8	1.25	
Base emitter voltage (nonsaturated) (absolute value of differential)	3066	Test condition B $V_{CE} = 5 \text{ V dc}$; $I_C = 10 \text{ }\mu\text{A dc}$ (see 4.5.6)	$ V_{BE1} - V_{BE2} 1$		10	mV dc
Base emitter voltage (nonsaturated) (absolute value of differential)	3066	Test condition B $V_{CE} = 5 \text{ V dc}$; $I_C = 100 \text{ }\mu\text{A dc}$ (see 4.5.6)	$ V_{BE1} - V_{BE2} 2$		6	mV dc
Base emitter voltage (nonsaturated) (absolute value of differential)	3066	Test condition B $V_{CE} = 5 \text{ V dc}$; $I_C = 10 \text{ mA dc}$ (see 4.5.6)	$ V_{BE1} - V_{BE2} 3$		10	mV dc
Subgroup 2						
Total dose irradiation	1019	Gamma exposure $V_{CES} = 48 \text{ V}$				
Collector to base cutoff current	3036	Bias condition D; $V_{CB} = 60 \text{ V dc}$	I_{CBO1}		20	$\mu\text{A dc}$
Breakdown voltage, collector to emitter		Bias condition D; $I_C = 100 \text{ }\mu\text{A dc}$; pulsed (see 4.5.2)	$V_{(BR)CEO}$	60		V dc
Emitter to base cutoff current	3061	Bias condition D, $V_{EB} = 5 \text{ V dc}$	I_{EBO1}		20	$\mu\text{A dc}$
Collector to base cutoff current	3036	Bias condition D, $V_{CB} = 50 \text{ V dc}$	I_{CBO2}		20	nA dc
Emitter to base cutoff current	3061	Bias condition D, $V_{EB} = 4 \text{ V dc}$	I_{EBO2}		20	nA dc
Forward-current transfer ratio 2N3811, 2N3811L, U only	3076	$V_{CE} = 5 \text{ V dc}$; $I_C = 1 \text{ }\mu\text{A dc}$	$[h_{FE1}] \text{ } \underline{5/}$	[37.5]		
Forward-current transfer ratio 2N3810, 2N3810L, U 2N3811, 2N3811L, U	3076	$V_{CE} = 5 \text{ V dc}$; $I_C = 10 \text{ }\mu\text{A dc}$	$[h_{FE2}] \text{ } \underline{5/}$	[50] [112.5]		
Forward-current transfer ratio 2N3810, 2N3810L, U 2N3811, 2N3811L, U	3076	$V_{CE} = 5 \text{ V dc}$; $I_C = 100 \text{ }\mu\text{A dc}$	$[h_{FE3}] \text{ } \underline{5/}$	[75] [150]	450 900	

See footnotes at end of table.

TABLE II. Group D inspection - Continued.

Inspection <u>1/</u> <u>2/</u> <u>3/</u>	MIL-STD-750		Symbol	Limit		Unit
	Method	Conditions		Min	Max	
<u>Subgroup 2</u> - Continued.						
Forward-current transfer ratio 2N3810, 2N3810L, U 2N3811, 2N3811L, U	3076	V _{CE} = 5 V dc; I _C = 1 mA dc	[h _{FE4}] <u>5/</u>	[75] [150]	450 900	
Forward-current transfer ratio 2N3810, 2N3810L, U 2N3811, 2N3811L, U	3076	V _{CE} = 5 V dc; I _C = 10 mA dc	[h _{FE5}] <u>5/</u>	[62.5] [125]		
Collector to emitter voltage (saturated)	3071	I _C = 100 μA dc, I _B = 10 μA dc	V _{CE(sat)1}		0.23	V dc
Collector to emitter voltage (saturated)	3071	I _C = 1 mA dc, I _B = 100 μA dc	V _{CE(sat)2}		0.29	V dc
Base-emitter voltage (saturated)	3066	Test condition A; I _C = 100 μA dc, I _B = 10 μA dc	V _{BE(sat)1}		0.81	V dc
Base-emitter voltage (saturated)	3066	Test condition A; I _C = 1 mA dc, I _B = 100 μA dc	V _{BE(sat)2}		0.92	V dc
Base-emitter voltage (nonsaturated)	3066	Test condition B; V _{CE} = 5 V dc; I _C = 100 μA dc	V _{BE(ON)}		0.81	V dc
Forward-current transfer ratio (gain ratio)	3076	V _{CE} = 5 V dc; I _C = 100 μA dc (see 4.5.5)	h _{FE3-1} / h _{FE3-2}	0.8	1.25	
Base emitter voltage (nonsaturated) (absolute value of differential)	3066	Test condition B V _{CE} = 5 V dc; I _C = 10 μA dc (see 4.5.6)	V _{BE1} - V _{BE2} 1		10	mV dc
Base emitter voltage (nonsaturated) (absolute value of differential)	3066	Test condition B V _{CE} = 5 V dc; I _C = 100 μA dc (see 4.5.6)	V _{BE1} - V _{BE2} 2		6	mV dc
Base emitter voltage (nonsaturated) (absolute value of differential)	3066	Test condition B V _{CE} = 5 V dc; I _C = 10 mA dc (see 4.5.6)	V _{BE1} - V _{BE2} 3		10	mV dc

1/ Tests to be performed on all devices receiving radiation exposure.

2/ For sampling plan, see MIL-PRF-19500.

3/ Electrical characteristics apply to the corresponding U suffix versions unless otherwise noted.

4/ See 6.2.e herein.

5/ See method 1019 of MIL-STD-750 for how to determine $[h_{FR}]$ by first calculating the delta ($1/h_{FE}$) from the pre- and Post-radiation h_{FE} . Notice the $[h_{FE}]$ is not the same as h_{FE} and cannot be measured directly. The $[h_{FE}]$ value can never exceed the pre-radiation minimum h_{FE} that it is based upon.

TABLE III. Group E inspection (all quality levels) - for qualification or re-qualification only.

Inspection	MIL-STD-750		Qualification
	Method	Conditions	
<u>Subgroup 1</u>			45 devices c = 0
Temperature cycling (air to air)	1051	Test condition C, 500 cycles	
Hermetic seal	1071		
Fine leak Gross leak			
Electrical measurements		See table I , subgroup 2 and 4.5.3 herein	
<u>Subgroup 2</u>			45 devices c = 0
Intermittent life	1037	Intermittent operation life: $V_{CB} = 10$ V dc, 6,000 cycles	
Electrical measurements		See table I , subgroup 2 and 4.5.3 herein	
<u>Subgroup 4</u>			Sample size N/A
Thermal response curves		See 4.2.2.1 herein.	
<u>Subgroup 5</u>			
Not applicable			
<u>Subgroup 8</u>			45 devices c = 0
Reverse stability	1033	Condition B	

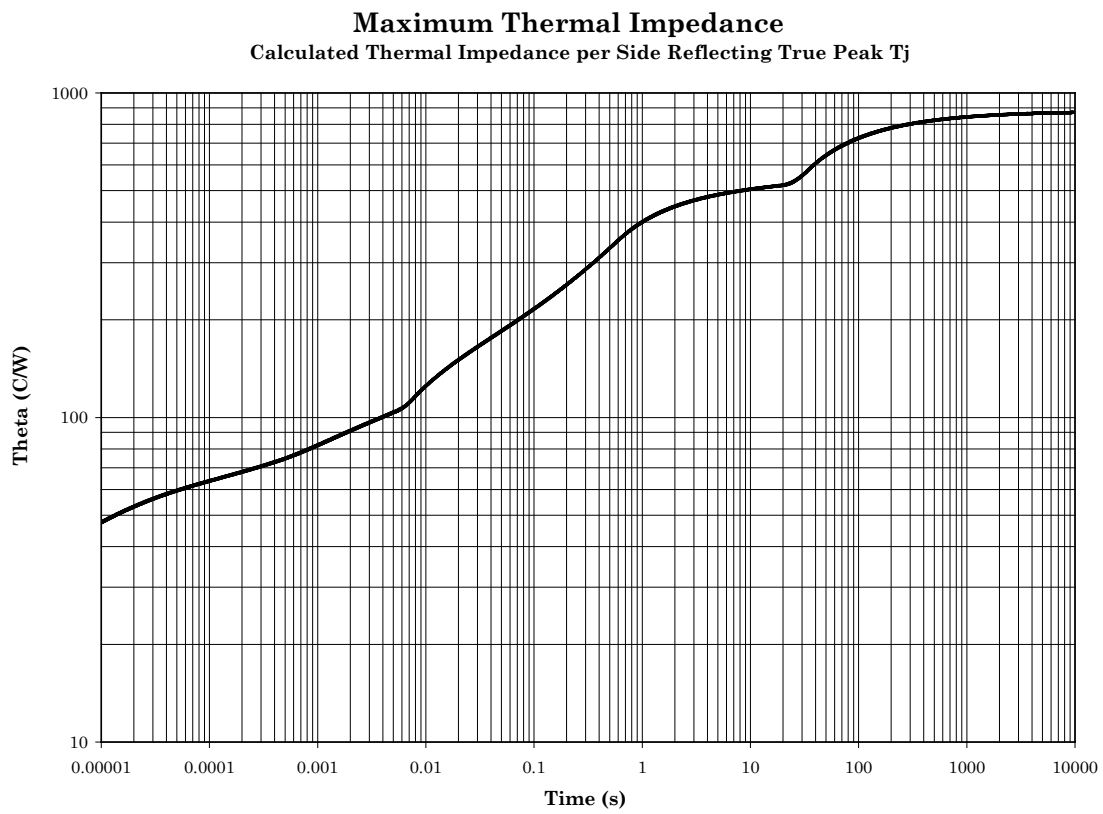


FIGURE 5. For each side: Thermal resistance (RHA) = 875°C/W, P_t = 200 mW.

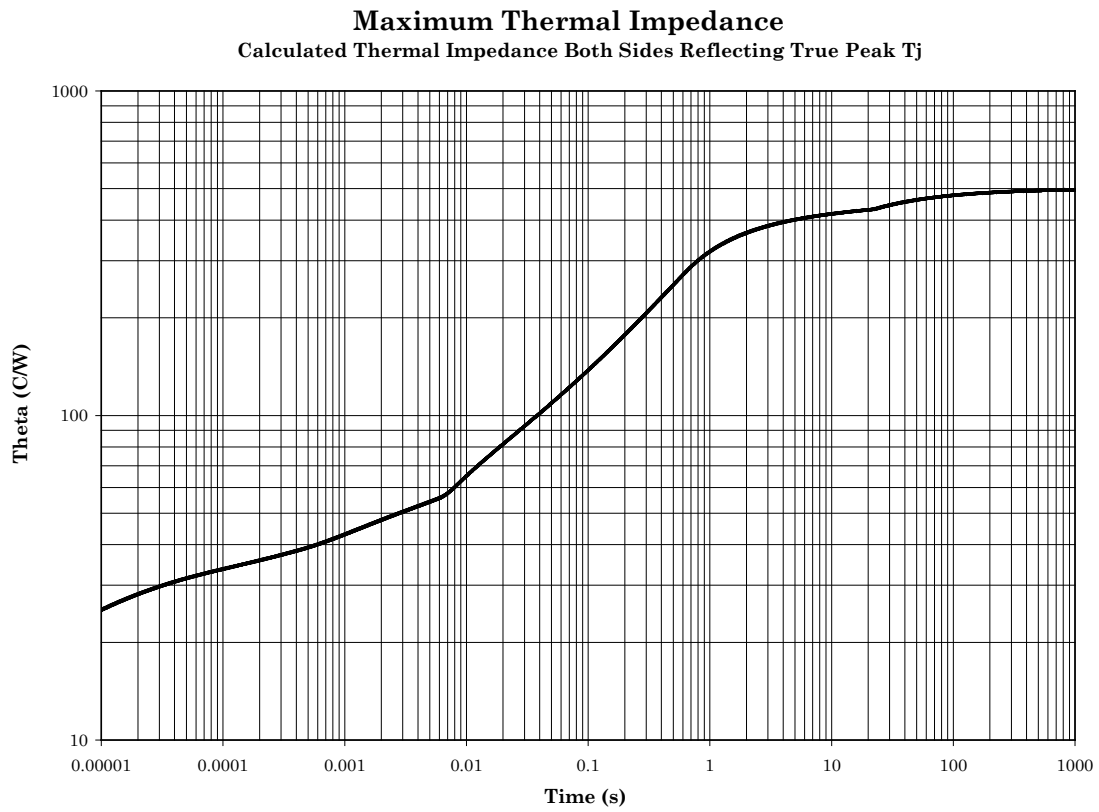


FIGURE 6. Both sides: Thermal resistance (RHA) = 500°C/W, Pt = 350 mW.

5. PACKAGING

5.1 Packaging. For acquisition purposes, the packaging requirements shall be as specified in the contract or order (see 6.2). When packaging of materiel is to be performed by DoD or in-house contractor personnel, these personnel need to contact the responsible packaging activity to ascertain packaging requirements. Packaging requirements are maintained by the Inventory Control Point's packaging activities within the Military Service or Defense Agency, or within the Military Service's system commands. Packaging data retrieval is available from the managing Military Department's or Defense Agency's automated packaging files, CD-ROM products, or by contacting the responsible packaging activity.

6. NOTES

(This section contains information of a general or explanatory nature that may be helpful, but is not mandatory. The notes specified in MIL-PRF-19500 are applicable to this specification.)

6.1 Intended use. Semiconductors conforming to this specification are intended for original equipment design applications and logistic support of existing equipment.

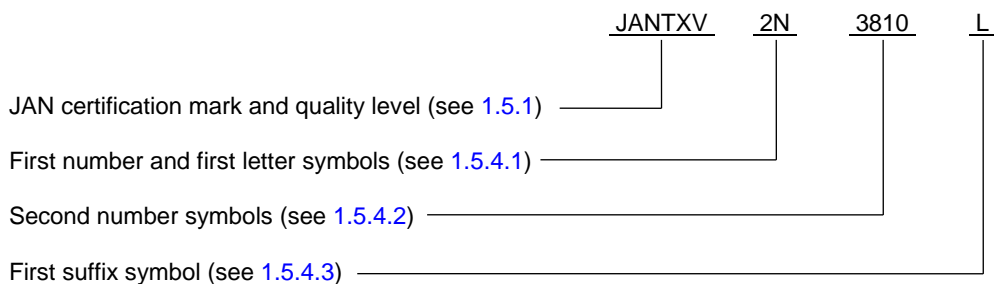
6.2 Acquisition requirements. Acquisition documents should specify the following:

- a. Title, number, and date of this specification.
- b. Packaging requirements (see 5.1).
- c. Lead finish (see 3.4.1).
- * d. The complete Part or Identifying Number (PIN), see 1.5 and 6.4.
- e. For acquisition of RHA designed devices, table II, subgroup 1 testing of group D is optional. If subgroup 1 testing is desired, it must be specified in the contract.

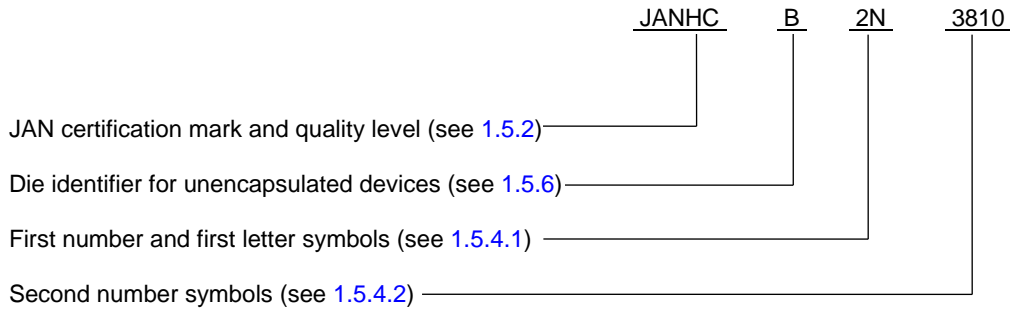
6.3 Qualification. With respect to products requiring qualification, awards will be made only for products which are, at the time of award of contract, qualified for inclusion in Qualified Manufacturers List (QML 19500) whether or not such products have actually been so listed by that date. The attention of the contractors is called to these requirements, and manufacturers are urged to arrange to have the products that they propose to offer to the Federal Government tested for qualification in order that they may be eligible to be awarded contracts or orders for the products covered by this specification. Information pertaining to qualification of products may be obtained from DLA Land and Maritime, ATTN: VQE, P.O. Box 3990, Columbus, OH 43218-3990 or e-mail vqe.chief@dla.mil. An online listing of products qualified to this specification may be found in the Qualified Products Database (QPD) at <https://assist.dla.mil>.

* 6.4 PIN construction example.

* 6.4.1 Encapsulated devices The PINs for encapsulated devices are constructed using the following form.



- * 6.4.2 Un-encapsulated devices. The PINs for un-encapsulated devices are constructed using the following form.



- * 6.5 List of PINs.

- * 6.5.1 List of PINs for encapsulated devices. The following is a list of possible PINs available on this specification sheet.

PINs for types 2N3810	PINs for type 2N3811
JAN2N3810	JAN2N3811
JAN2N3810L	JAN2N3811L
JAN2N3810U	JAN2N3811U
JANTX2N3810	JANTX2N3811
JANTX2N3810L	JANTX2N3811L
JANTX2N3810U	JANTX2N3811U
JANTXV#2N3810 (1)	JANTXV#2N3811 (1)
JANTXV#2N3810L (1)	JANTXV#2N3811L (1)
JANTXV#2N3810U (1)	JANTXV#2N3811U (1)
JANS#2N3810 (1)	JANS#2N3811 (1)
JANS#2N3810L (1)	JANS#2N3811L (1)
JANS#2N3810U (1)	JANS#2N3811U (1)

- (1) The number sign (#) represent one of eight RHA designators available "M", "D", "P", "L", "R", "F", "G", and "H".

- * 6.5.2 List of PINs for unencapsulated devices. The following is a list of possible PINs available on this specification sheet. The qualified die suppliers with the applicable letter version (e.g., JANHCA2N3810) will be identified on the QML.

Die ordering information		
PIN	Manufacturer	
	43611	34156
2N3810	JANHCA#2N3810 JANKCA#2N3810	JANHCB#2N3810 JANKCB#2N3810
2N3811	JANHCA#2N3811 JANKCA#2N3811	JANHCB#2N3811 JANKCB#2N3811

- (1) The number sign (#) represent one of eight RHA designators available "M", "D", "P", "L", "R", "F", "G", and "H".

6.6 Changes from previous issue. The margins of this specification are marked with asterisks to indicate where changes from the previous issue were made. This was done as a convenience only and the Government assumes no liability whatsoever for any inaccuracies in these notations. Bidders and contractors are cautioned to evaluate the requirements of this document based on the entire content irrespective of the marginal notations and relationship to the last previous issue.

Custodians:
 Army - CR
 Navy - EC
 Air Force - 85
 NASA - NA
 DLA - CC

Preparing activity:
 DLA - CC

(Project 5961-2015-029)

Review activities:
 Army - AR, MI
 Navy - AS, MC
 Air Force - 19, 71, 99

NOTE: The activities listed above were interested in this document as of the date of this document. Since organizations and responsibilities can change, you should verify the currency of the information above using the ASSIST Online database at <https://assist.dla.mil>.